FAIRCHILD SEMICONDUCTOR®

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# 74VHCT240A
# Octal Buffer/Line Driver with 3-STATE Outputs

## Features

- High Speed: $t_{PD}$ = 5.6ns (Typ.) at $V_{CC}$ = 5V
- Power down protection is provided on inputs and outputs
- Low power dissipation: $I_{CC}$ = 4µA (Max.) @ $T_A$ = 25°C
- Pin and function compatible with 74HCT240

## General Description

The VHCT240A is an advanced high speed CMOS octal bus transceiver fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation. The VHCT240A is an inverting 3-STATE buffer having two active-LOW output enables. This device is designed to be used as 3-STATE memory address drivers, clock drivers, and bus oriented transmitter/ receivers.

Protection circuits ensure that 0V to 7V can be applied to the input and output(1) pins without regard to the supply voltage. These circuits prevent device destruction due to mismatched supply and input/output voltages. This device can be used to interface 5V to 3V systems and two supply systems such as battery back up.

**Note:**

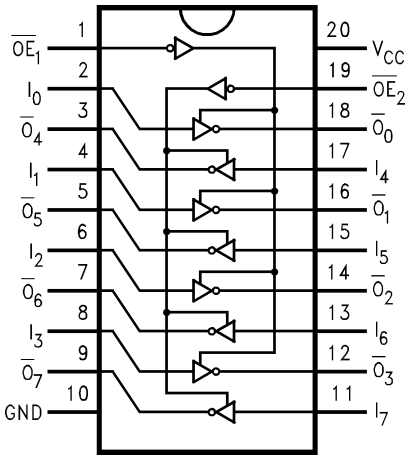
1. Outputs in OFF-State

## Ordering Information

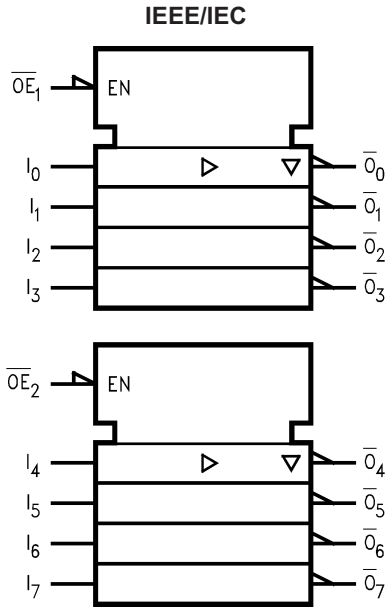
| Order Number | Package Number | Package Description |
|---|---|---|
| 74VHCT240AM | M20B | 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide |
| 74VHCT240ASJ | M20D | 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| 74VHCT240AMTC | MTC20 | 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |

Surface mount packages are also available on Tape and Reel. Specify by appending the suffix letter “X” to the ordering number. Pb-Free package per JEDEC J-STD-020B.

## Connection Diagram




## Logic Symbol




## Pin Description

| Pin Names | Description |
|---|---|
| $\overline{OE}_1$, $\overline{OE}_2$ | 3-STATE Output Enable |
| $I_0$–$I_7$ | Inputs |
| $\overline{O}_0$–$\overline{O}_7$ | Outputs 3-STATE Outputs |

## Truth Tables

| Inputs | | Outputs (Pins 12, 14, 16, 18) |
|---|---|---|
| $\overline{OE}_1$ | $I_n$ | |
| L | L | H |
| L | H | L |
| H | X | Z |

| Inputs | | Outputs (Pins 3, 5, 7, 9) |
|---|---|---|
| $\overline{OE}_1$ | $I_n$ | |
| L | L | H |
| L | H | L |
| H | X | Z |

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | Rating |
|---|---|---|
| $V_{CC}$ | Supply Voltage | –0.5V to +7.0V |
| $V_{IN}$ | DC Input Voltage | –0.5V to +7.0V |
| $V_{OUT}$ | DC Output Voltage<br>Note 2<br>Note 3 | <br>–0.5V to $V_{CC}$ + 0.5V<br>–0.5V to +7.0V |
| $I_{IK}$ | Input Diode Current | –20mA |
| $I_{OK}$ | Output Diode Current(4) | ±20mA |
| $I_{OUT}$ | DC Output Current | ±25mA |
| $I_{CC}$ | DC $V_{CC}$ / GND Current | ±75mA |
| $T_{STG}$ | Storage Temperature | –65°C to +150°C |
| $T_L$ | Lead Temperature (Soldering, 10 seconds) | 260°C |

## Recommended Operating Conditions(5)

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

| Symbol | Parameter | Rating |
|---|---|---|
| $V_{CC}$ | Supply Voltage | 4.5V to +5.5V |
| $V_{IN}$ | Input Voltage | 0V to +5.5V |
| $V_{OUT}$ | Output Voltage<br>Note 2<br>Note 3 | <br>0V to $V_{CC}$<br>0V to +5.5V |
| $T_{OPR}$ | Operating Temperature | –40°C to +85°C |
| $t_r$, $t_f$ | Input Rise and Fall Time, $V_{CC}$ = 5.0V ± 0.5V | 0ns/V ~ 20ns/V |

**Notes:**

2. HIGH or LOW state. $I_{OUT}$ absolute maximum rating must be observed.
3. When outputs are in OFF-State or when $V_{CC}$ = 0V.
4. $V_{OUT}$ < GND, $V_{OUT}$ > $V_{CC}$ (Outputs Active).
5. Unused inputs must be held HIGH or LOW. They may not float.

## DC Electrical Characteristics

| Symbol | Parameter | $V_{CC}$ (V) | Conditions | | $T_A = 25°C$ | | | $T_A = -40°C$ to +85°C | | Units |
|---|---|---|---|---|---|---|---|---|---|---|
| | | | | | Min. | Typ. | Max. | Min. | Max. | |
| $V_{IH}$ | HIGH Level Input Voltage | 4.5 | | | 2.0 | | | 2.0 | | V |
| | | 5.5 | | | 2.0 | | | 2.0 | | |
| $V_{IL}$ | LOW Level Input Voltage | 4.5 | | | | | 0.8 | | 0.8 | V |
| | | 5.5 | | | | | 0.8 | | 0.8 | |
| $V_{OH}$ | HIGH Level Output Voltage | 4.5 | $V_{IN} = V_{IH}$ or $V_{IL}$ | $I_{OH} = -50\mu A$ | 4.40 | 4.50 | | 4.40 | | V |
| | | | | $I_{OH} = -8mA$ | 3.94 | | | 3.80 | | |
| $V_{OL}$ | LOW Level Output Voltage | 4.5 | $V_{IN} = V_{IH}$ or $V_{IL}$ | $I_{OL} = 50\mu A$ | | 0.0 | 0.1 | | 0.1 | V |
| | | | | $I_{OL} = 8mA$ | | | 0.36 | | 0.44 | |
| $I_{OZ}$ | 3-STATE Output Off-State Current | 5.5 | $V_{IN} = V_{IH}$ or $V_{IL}$, $V_{OUT} = V_{CC}$ or GND | | | | ±0.25 | | ±2.5 | μA |
| $I_{IN}$ | Input Leakage Current | 0–5.5 | $V_{IN} = 5.5V$ or GND | | | | ±0.1 | | ±1.0 | μA |
| $I_{CC}$ | Quiescent Supply Current | 5.5 | $V_{IN} = V_{CC}$ or GND | | | | 4.0 | | 40.0 | μA |
| $I_{CCT}$ | Maximum $I_{CC}$ / Input | 5.5 | $V_{IN} = 3.4V$, Other Input = $V_{CC}$ or GND | | | | 1.35 | | 1.50 | mA |
| $I_{OFF}$ | Output Leakage Current (Power Down State) | 0.0 | $V_{OUT} = 5.5V$ | | | | 0.5 | | 5.0 | μA |

## Noise Characteristics

| Symbol | Parameter | $V_{CC}$ (V) | Conditions | $T_A = 25°C$ | | Units |
|---|---|---|---|---|---|---|
| | | | | Typ. | Limits | |
| $V_{OLP}$(6) | Quiet Output Maximum Dynamic $V_{OL}$ | 5.0 | $C_L = 50pF$ | 0.9 | 1.1 | V |
| $V_{OLV}$(6) | Quiet Output Minimum Dynamic $V_{OL}$ | 5.0 | $C_L = 50pF$ | –0.9 | –1.1 | V |
| $V_{IHD}$(6) | Minimum HIGH Level Dynamic Input Voltage | 5.0 | $C_L = 50pF$ | | 2.0 | V |
| $V_{ILD}$(6) | Maximum LOW Level Dynamic Input Voltage | 5.0 | $C_L = 50pF$ | | 0.8 | V |

**Note:**

6. Parameter guaranteed by design.

## AC Electrical Characteristics

| Symbol | Parameter | $V_{CC}$ (V) | Conditions | | $T_A = 25°C$ | | | $T_A = -40°C$ to $+85°C$ | | Units |
|---|---|---|---|---|---|---|---|---|---|---|
| | | | | | Min. | Typ. | Max. | Min. | Max. | |
| $t_{PLH}$, $t_{PHL}$ | Propagation Delay Time | 5.0 ± 0.5 | | $C_L = 15pF$ | | 5.6 | 7.8 | 1.0 | 9.0 | ns |
| | | | | $C_L = 50pF$ | | 6.1 | 8.8 | 1.0 | 10.0 | |
| $t_{PZL}$, $t_{PZH}$ | 3-STATE Output Enable Time | 5.0 ± 0.5 | $R_L = 1k\Omega$ | $C_L = 15pF$ | | 6.5 | 10.4 | 1.0 | 12.5 | ns |
| | | | | $C_L = 50pF$ | | 7.3 | 11.4 | 1.0 | 13.5 | |
| $t_{PLZ}$, $t_{PHZ}$ | 3-STATE Output Disable Time | 5.0 ± 0.5 | $R_L = 1k\Omega$ | $C_L = 50pF$ | | 7.0 | 11.4 | 1.0 | 13.0 | ns |
| $t_{OSLH}$, $t_{OSHL}$ | Output to Output Skew | 5.0 ± 0.5 | (7) | | | | 1.0 | | 1.0 | ns |
| $C_{IN}$ | Input Capacitance | | $V_{CC}$ = Open | | | 4 | 10 | | 10 | pF |
| $C_{OUT}$ | Output Capacitance | | $V_{CC}$ = 5.0V | | | 9 | | | | pF |
| $C_{PD}$ | Power Dissipation Capacitance | | (8) | | | 19 | | | | pF |

**Notes:**

7. Parameter guaranteed by design. $t_{OSLH} = |t_{PLH\ max} - t_{PLH\ min}|$; $t_{OSHL} = |t_{PHL\ max} - t_{PHL\ min}|$

8. $C_{PD}$ is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC}$ (Opr.) = $C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC} / 8$ (per F/F). The total $C_{PD}$ when n pcs. of the Octal D Flip-Flop operates can be calculated by the equation: $C_{PD}$ (total) = 20 + 12n

## Physical Dimensions

Dimensions are in millimeters unless otherwise noted.

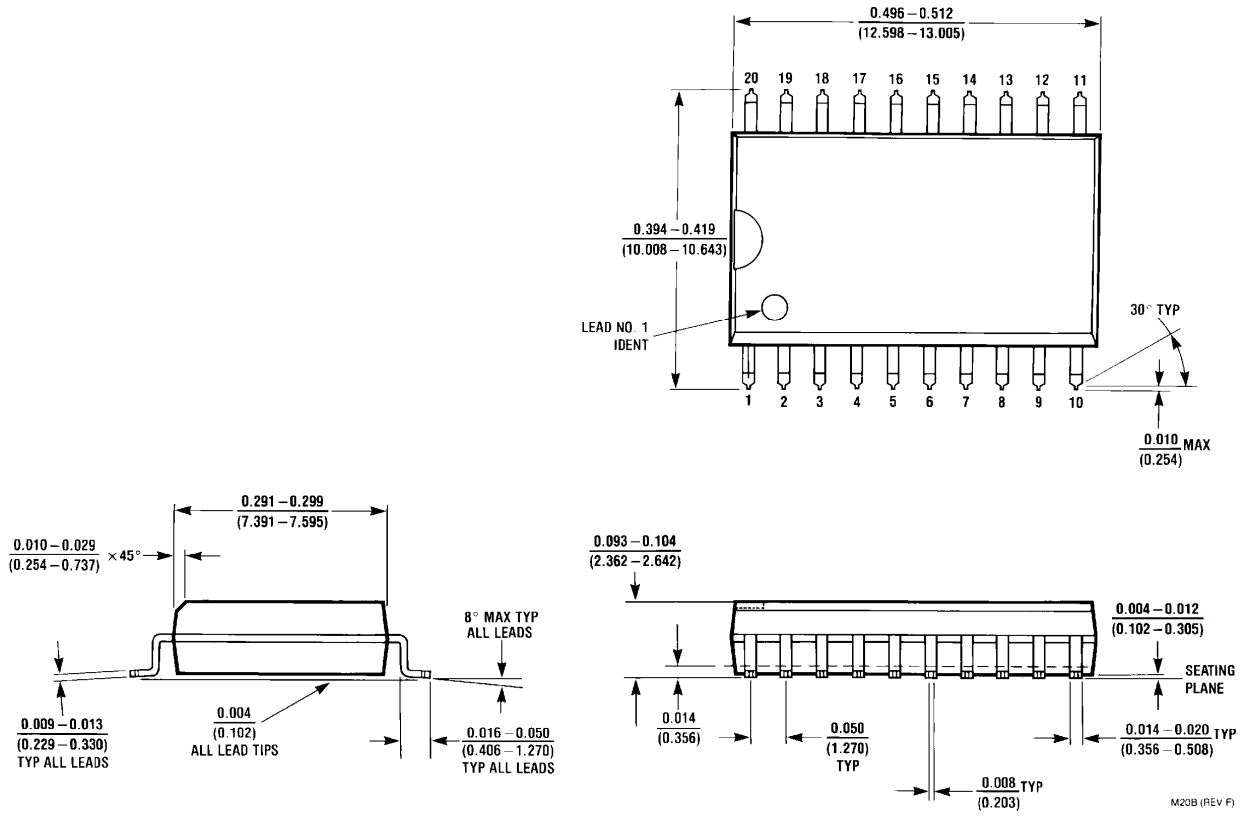
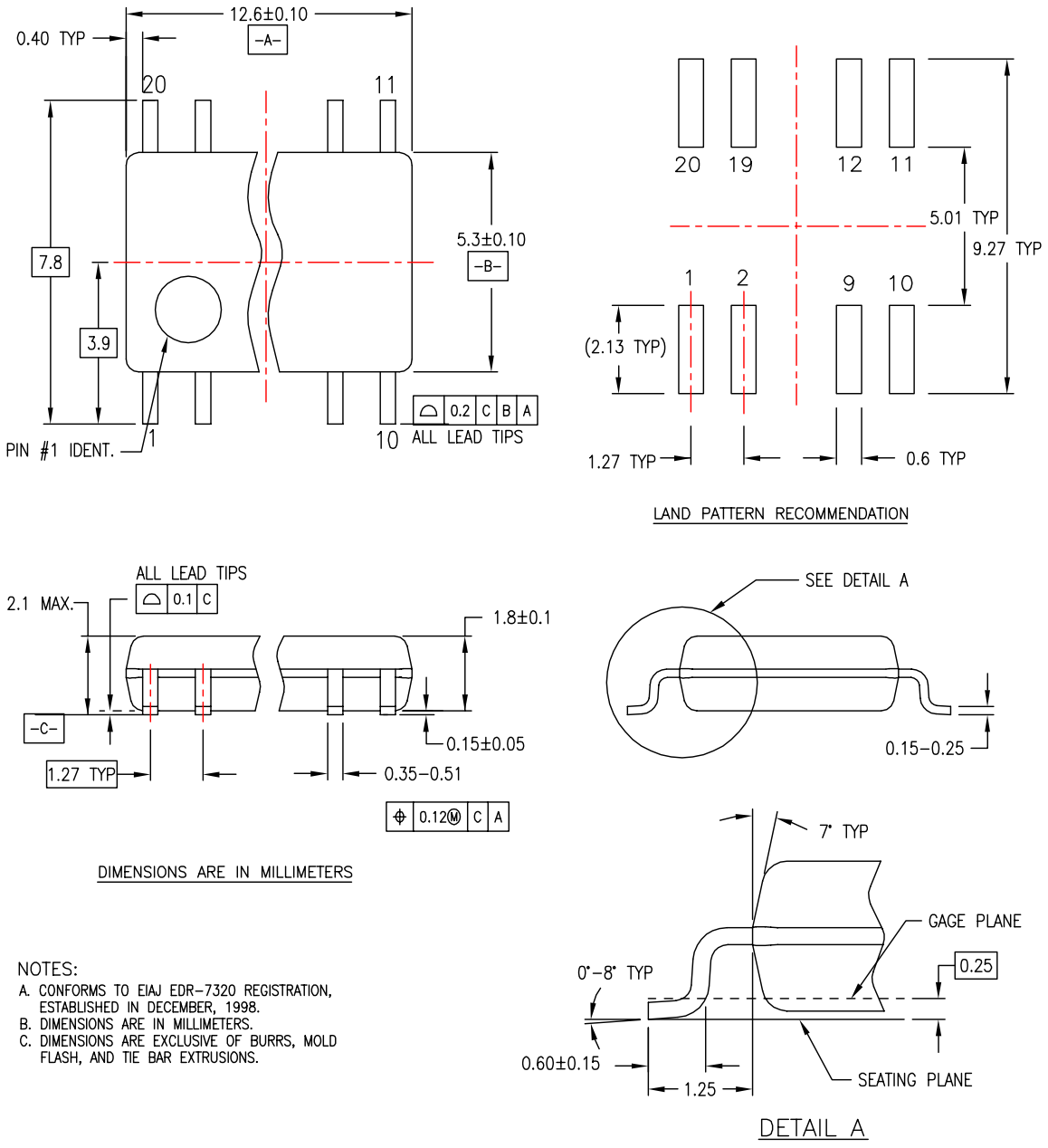



**Figure 1. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide**
**Package Number M20B**

## Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.




NOTES:

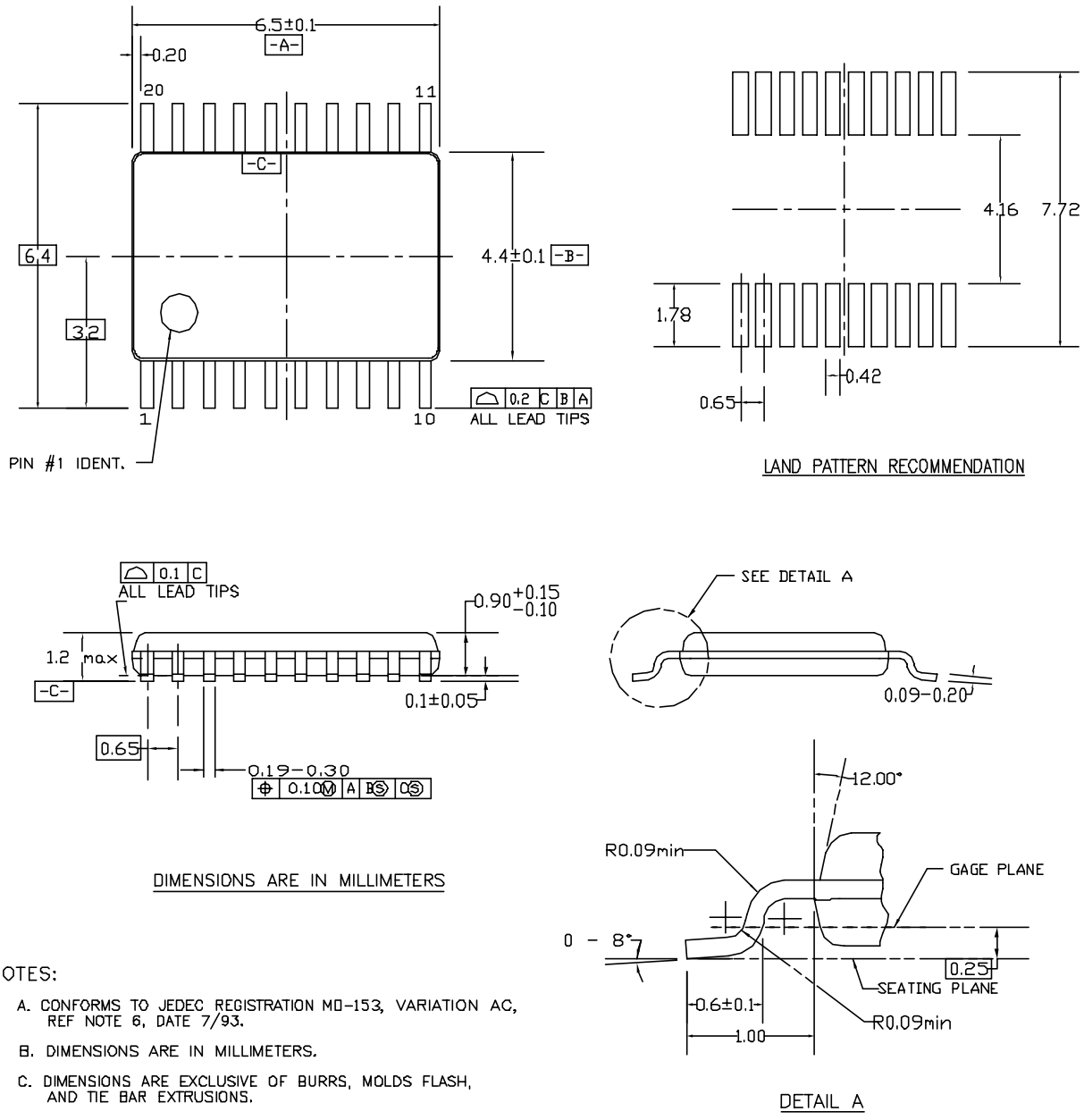
A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DREVC

**Figure 2. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide**
**Package Number M20D**

## Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.




NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.

D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REVD1

**Figure 3. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide**
**Package Number MTC20**

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SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SyncFET™
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